



QUALCOMM

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Ms. Susanna Kooistra
Mr. Patrick Merias
ETSI, MCC
650, route des Lucioles
Sophia-Antipolis
France

Subject: Nomination of candidate for the 3GPP TSG RAN5 Vice Chairman

Dear Ms. Kooistra and Mr. Merias:

I am pleased to inform you that Qualcomm, through its ATIS 3GPP affiliation, is nominating Mr. Pradeep Gowda as candidate for the position of 3GPP TSG RAN5 Vice Chairman at the upcoming election in RAN5#69.

Pradeep will be trained to comply with all applicable antitrust/competition laws and regulations while acting in his capacity as TSG RAN WG5 Vice Chairman.

In proposing Pradeep Gowda for the position of 3GPP TSG RAN5 Vice Chairman, Qualcomm is committed to support Pradeep in this role and to support all obligations of the Vice Chairman including time and travel commitments.

A brief curriculum vitae of Pradeep Gowda is attached.

Best Regards,

Edward G. Tiedemann, Jr.
Senior Vice-President, Engineering
QUALCOMM Technologies, Inc.

Pradeep Gowda

Pradeep has been working at QUALCOMM since 2001 and has been involved in RF and Layer1 conformance testing of LTE, CDMA2000, WCDMA and GERAN chipsets. For the last 14 years he has been leading RF and Layer1 system testing activities, coordinating and planning Layer1 and RF verification activities with cross functional teams (involving Systems, SW and HW engineers).

In November 2008, he started attending RAN WG5 meetings and has been actively contributing to RF and Layer1 aspects of HSPA, DC-HSDPA and LTE specifications over the last 7 years.

During this time, he actively contributed and enabled the completion of several RAN5 LTE and HSPA Work items

Currently Pradeep is the Vice Chairman of the TSG RAN WG5 and is the convenor of the RF/RRM group for the last 2 years.

Pradeep graduated in 2001 with a Master's degree in Electrical Engineering from State University of New York Buffalo, USA.